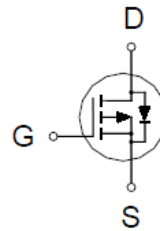


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P-Channel Logic Level Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-12V	20mΩ @ $V_{GS} = -4.5V$	-32A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-12	V
Gate-Source Voltage		V_{GS}	±8	
Continuous Drain Current ²	$T_C = 25\text{ °C}$	I_D	-32	A
	$T_C = 100\text{ °C}$		-20	
	$T_A = 25\text{ °C}$		-9	
	$T_A = 70\text{ °C}$		-7	
Pulsed Drain Current ¹		I_{DM}	-60	
Avalanche Current		I_{AS}	-36.7	
Avalanche Energy	L = 0.1mH	E_{AS}	67.5	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	31	W
	$T_C = 100\text{ °C}$		12	
	$T_A = 25\text{ °C}$		2	
	$T_A = 70\text{ °C}$		1.3	
Operating Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

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THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ³	Steady-State	$R_{\theta JA}$		60	°C / W
Junction-to-Ambient	Steady-State	$R_{\theta JC}$		4	

¹Pulse width limited by maximum junction temperature.

²Package limitation current is 30A.

³The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-12			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.40	-0.50	-0.85	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -12V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -10V, V_{GS} = 0V, T_J = 55^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = -5V, V_{GS} = -10V$	-60			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = -2.5V, I_D = -8.5A$		14	25	m Ω
		$V_{GS} = -4.5V, I_D = -9A$		11	20	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -9A$		49		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -10V, f = 1\text{MHz}$		2840		pF
Output Capacitance	C_{oss}			599		
Reverse Transfer Capacitance	C_{rss}			579		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1\text{MHz}$		2.9		Ω
Total Gate Charge ²	$Q_g(V_{GS}=-4.5V)$	$V_{DS} = 0.5V_{(BR)DSS}, I_D = -9A$		38		nC
	$Q_g(V_{GS}=-2.5V)$			24		
Gate-Source Charge ²	Q_{gs}			3.2		
Gate-Drain Charge ²	Q_{gd}			11.2		
Turn-On Delay Time ²	$t_{d(on)}$		$V_{DS} = -10V, I_D \cong -1A, V_{GS} = -4.5V, R_{GS} = 6\Omega$		35	
Rise Time ²	t_r			70		
Turn-Off Delay Time ²	$t_{d(off)}$			200		
Fall Time ²	t_f			105		

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SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)

Continuous Current ³	I _S			-60	A
Forward Voltage ¹	V _{SD}	I _F = -9A, V _{GS} = 0V		-1	V
Reverse Recovery Time	t _{rr}	I _F = -9A, di _F /dt = 100A / μS		60	nS
Reverse Recovery Charge	Q _{rr}			52	nC

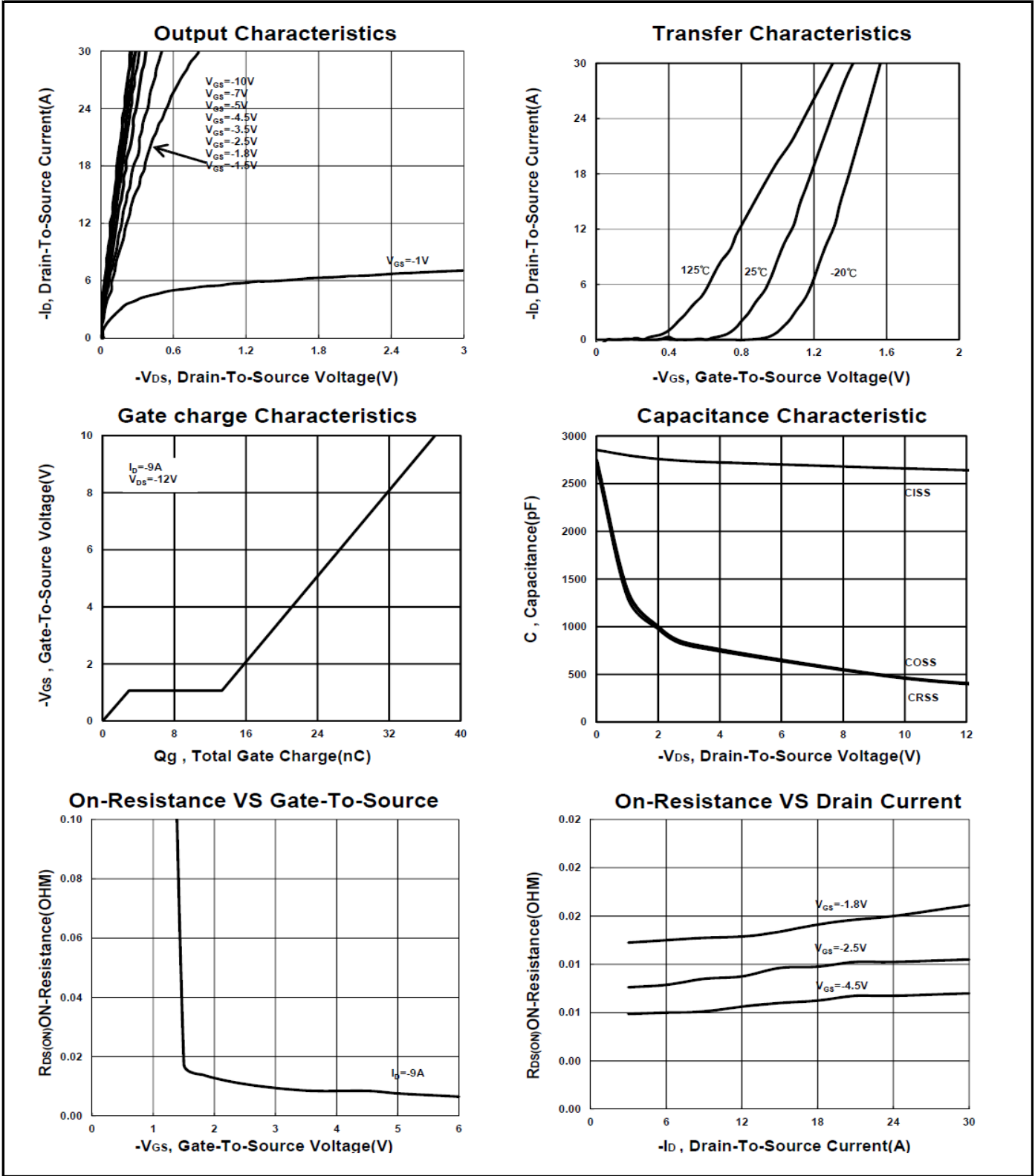
¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

³Package limitation current is 30A.

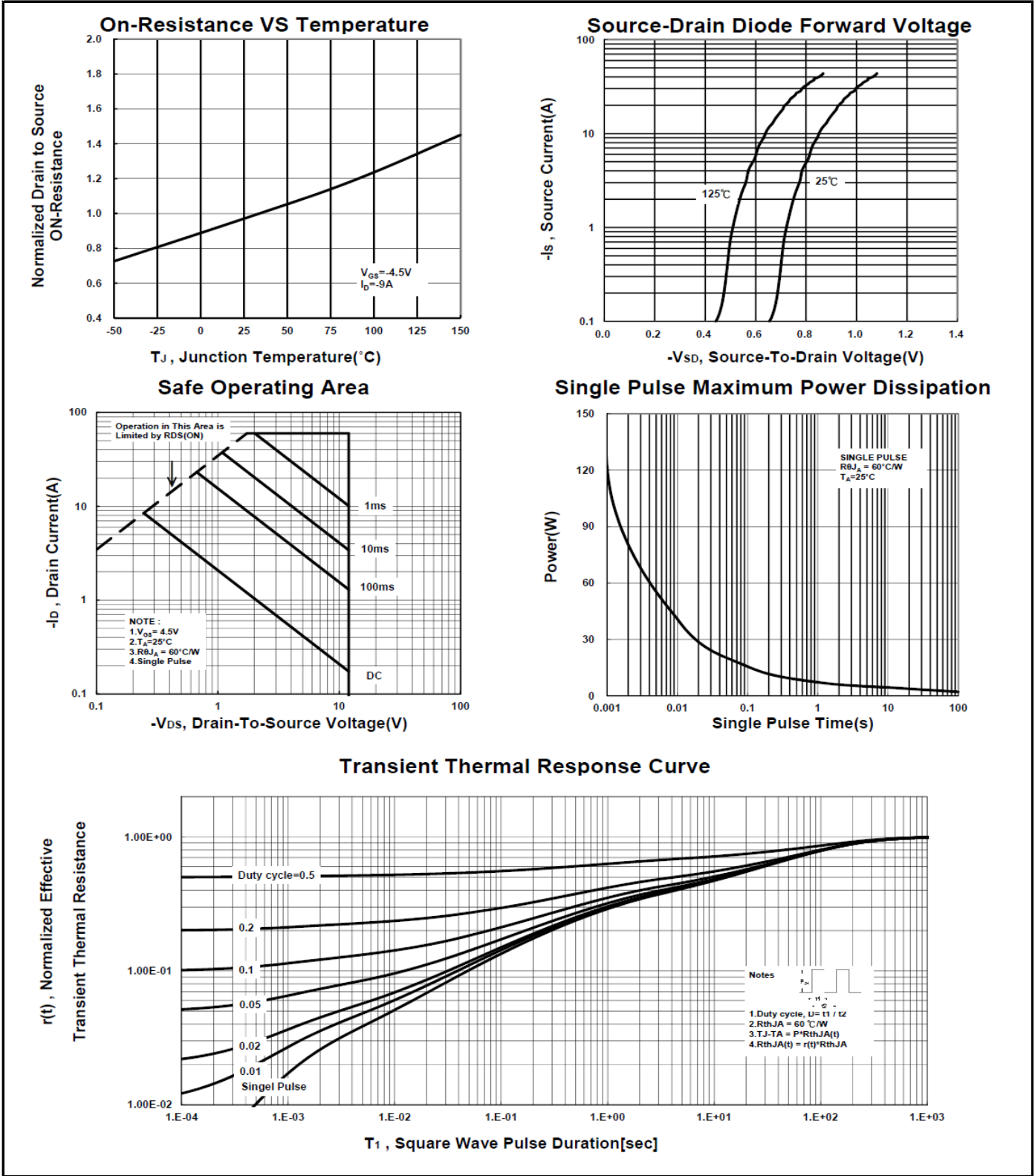
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Package Dimension

PDFN 3x3P MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	3		3.6	I	0.7		1.12
B	2.88		3.2	J	0.1		0.33
C	2.9		3.2	K	0.6		
D	1.98		2.69	L	0°	10°	12°
E	3		3.6	M	0.14		0.41
F	0		0.455	N	0.6		0.7
G	1.47		2.2	O	0.12		0.36
H	0.15		0.56	P	0		0.2

